Application Serial No: 10/598,903
Responsive to the Office Action mailed on: August 15, 2008

IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A driver module structure comprising:

a flexible circuit board provided with a wiring pattern;

a semiconductor device mounted on the flexible circuit board; and

an electrically conductive heat-radiating member joined to the semiconductor device,

wherein the wiring pattern comprises a ground wiring pattern,

the flexible circuit board has a cavity that exposes a portion of the ground wiring pattern,

the exposed portion of the ground wiring pattern and the heat-radiating member are connected to establish electrical continuity via a member that is fitted into the cavity, and

the cavity is a through hole penetrating the ground wiring pattern, a portion of the ground wiring pattern on an opposite side from the heat-radiating member is exposed, and the member fitted into the cavity is ~~a~~ an electrically conductive screw ~~for fastening~~ that fastens the flexible circuit board and the heat-radiating member and provides electrical continuity between the exposed portion of the ground wiring pattern and the heat-radiating member.

2. (Withdrawn) The driver module structure according to claim 1, wherein the cavity is a recess for exposing a portion of the ground wiring pattern to the heat-radiating member, and the member fitted into the cavity is a projection of the heat-radiating member.

3. (Withdrawn) The driver module structure according to claim 2, wherein the exposed portion of the ground wiring pattern and the projection are connected via an electrically conductive bonding material.

4. (Withdrawn) The driver module structure according to claim 1, wherein the cavity is a through hole penetrating the ground wiring pattern, a portion of the ground wiring pattern on an opposite side from the heat-radiating member is exposed, and the member fitted into the cavity is a projection of the heat-radiating member.

5. (Withdrawn) The driver module structure according to claim 4, wherein the projection is hollow, and an end of the projection is deformed so that the exposed portion of the ground wiring pattern and the projection are connected to establish electrical continuity.

6. (Withdrawn) The driver module structure according to claim 4, wherein the exposed portion of the ground wiring pattern and the projection are connected via an electrically conductive bonding material.

7. (Cancelled)

8. (Previously Presented) The driver module structure according to claim 1, wherein the exposed portion of the ground wiring pattern and the screw are connected via an electrically conductive bonding material.